

# 3-Phase Inverter Automotive Power Module FTCO3V455A1

#### **General Description**

The FTCO3V455A1 is a 40 V low R<sub>DS(ON)</sub> automotive qualified power module featuring a 3–phase MOSFET inverter optimized for 12 V battery systems. It includes a precision shunt resistor for current sensing an NTC for temperature sensing and an RC snubber circuit.

The module utilizes **onsemi**'s trench MOSFET technology and it is designed to provide a very compact and high performance variable speed motor drive for applications like electric power steering, electro-hydraulic power steering, electric water pumps, electric oil pumps. The power module is 100% lead free, RoHS and UL compliant.

#### **Features**

- 40 V 150 A 3–phase Trench MOSFET Inverter Bridge
- 1% Precision Shunt Current Sensing
- Temperature Sensing
- DBC Substrate
- 100% Lead Free and RoHS Compliant with 2000/53/C Directive
- UL94V-0 Compliant
- Isolation Rating of 2500 V rms/min
- Mounting Through Screws
- Automotive Qualified

#### Benefits

- Low Junction-sink Thermal Resistance
- Low Inverter Electrical Resistance
- High Current Handling
- Compact Motor Design
- Highly Integrated Compact Design
- Better EMC and Electrical Isolation
- Easy and Reliable Installation
- Improved Overall System Reliability

#### **Applications**

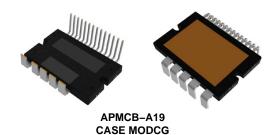
- Electric and Electro-Hydraulic Power Steering
- Electric Water Pump
- Electric Oil Pump
- Electric Fan

#### Flammability Information

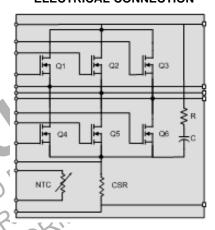
 All Materials Present in the Power Module Meet UL Flammability Rating Class 94 V-0 or Higher

#### Solder

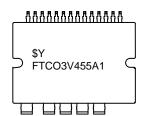
• Solder Used is a Lead Free SnAgCu Alloy



#### **ELECTRICAL CONNECTION**



#### **MARKING DIAGRAM**



\$Y FTCO3V455A1 = ON Semiconductor

= Specific Device Code

#### ORDERING INFORMATION

See detailed ordering and shipping information on page 8 of this data sheet.

#### ABSOLUTE MAXIMUM RATINGS (T<sub>J</sub> = 25°C, Unless Otherwise Specified)

Symbol	Parameter	Rating	Unit
V <sub>DS</sub> (Q1~Q6)	Drain to Source Voltage	40	V
V <sub>GS</sub> (Q1~Q6)	Gate to Source Voltage	±20	V
I <sub>D</sub> (Q1~Q6)	Drain Current Continuous (T <sub>C</sub> = 25°C, V <sub>GS</sub> = 10 V)	150	Α
E <sub>AS</sub> (Q1~Q6)	Single Pulse Avalanche Energy (Note 1)	947	mJ
P <sub>D</sub>	Power Dissipation	115	W
TJ	Maximum Junction Temperature	175	°C
T <sub>STG</sub>	Storage Temperature	125	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL RESISTANCE

Symbol	Parameter	Min.	Тур.	Max.	Unit
Rthjc	Q1 Thermal Resistance J –C		0.8	CNP	°C/W
Thermal Resistance Junction to case,	Q2 Thermal Resistance J –C	1-	0.8	1.1	°C/W
Single Inverter FET, chip center	Q3 Thermal Resistance J –C		0.8	1.1	°C/W
(Note 2)	Q4 Thermal Resistance J –C	7-5	0.8	1.1	°C/W
	Q5 Thermal Resistance J –C	2.Oh	0.8	1.1	°C/W
	Q6 Thermal Resistance J –C	-56	0.8	1.1	°C/W
T <sub>J</sub>	Maximum Junction Temperature	0,0	N.	175	°C
T <sub>S</sub>	Operating Sink Temperature	-40		120	°C
T <sub>STG</sub>	Storage Temperature	-40		125	°C

Starting T<sub>J</sub> = 25°C, V<sub>DS</sub> = 20 V, I<sub>AS</sub> = 64 A, L = 480 μH.
 These values are based on Thermal simulations and PV level measurements. These values assume a single MOSFET is on, and the test condition for referenced temperature is "Chip Center".

This measured between the T<sub>J</sub> of each MOSFET and the temperature of the case located immediately under the center THIS DEVICE PLEASENTAL of the chip.

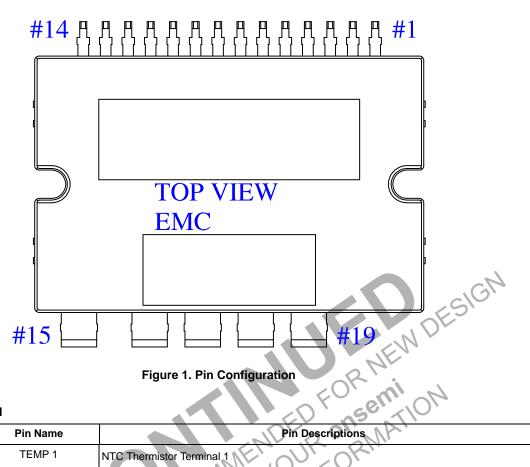
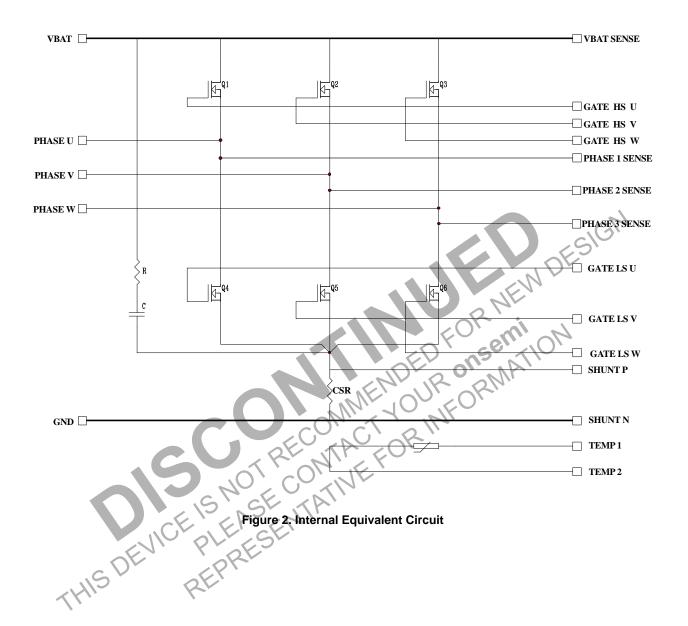


Figure 1. Pin Configuration

#### **PIN DESCRIPTION**

PIN DESCRIP	1014	
Pin Number	Pin Name	Pin Descriptions
1	TEMP 1	NTC Thermistor Terminal 1
2	TEMP 2	NTC Thermistor Terminal 2
3	PHASE W SENSE	Source of HS W and Drain of LS W
4	GATE HS W	Gate of HS phase W MOSFET
5	GATE LS W	Gate of LS phase W MOSFET
6	PHASE V SENSE	Source of HS V and Drain of LS V
7	GATE HS V	Gate of HS phase V MOSFET
8	GATE LS V	Gate of LS phase V MOSFET
9	PHASE U SENSE	Source of HS U and Drain of LS U
10	GATE HS U	Gate of HS phase U MOSFET
11	VBAT SENSE	Drain of HS U, V and W MOSFET
12	GATE LS U	Gate of LS phase U MOSFET
13	SHUNT P	Source of LS U, V W MOSFETS / Shunt +
14	SHUNT N	Negative shunt terminal (shunt –)
15	VBAT	Positive battery terminal
16	GND	Negative battery terminal
17	PHASE U	Motor phase U
18	PHASE V	Motor phase V
19	PHASE W	Motor phase W



## **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C, Unless Otherwise Specified)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
BVpss	D-S Breakdown Voltage (Inverter MOSFETs)	$V_{GS} = 0$ , $I_D = 250 \mu A$	40	-	-	V
Vgs	Gate to Source Voltage (Inverter MOSFETs)		-20	-	20	V
Vтн	Threshold Voltage (Inverter MOSFETs)	$V_{GS} = V_{DS}, I_D = 250 \mu A, T_j = 25^{\circ}C$	2.0	2.8	4.0	V
VsD	MOSFET Body Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 80 \text{ A}, T_j = 25^{\circ}\text{C}$		0.8	1.28	V
RDS(ON)Q1	Inverter High Side MOSFETs Q1 (See Note 3)	$V_{GS} = 10 \text{ V}, I_D = 80 \text{ A}, T_j = 25^{\circ}\text{C}$	-	1.15	1.66	mΩ
RDS(ON)Q2	Inverter High Side MOSFETs Q2 (See Note 3)	$V_{GS} = 10 \text{ V}, I_D = 80 \text{ A}, T_j = 25^{\circ}\text{C}$	-	1.22	1.73	mΩ
RDS(ON)Q3	Inverter High Side MOSFETs Q3 (See Note 3)	$V_{GS} = 10 \text{ V}, I_D = 80 \text{ A}, T_j = 25^{\circ}\text{C}$		1.31	1.82	mΩ
RDS(ON)Q4	Inverter Low Side MOSFETs Q4 (See Note 3)	$V_{GS} = 10 \text{ V}, I_D = 80 \text{ A}, T_j = 25^{\circ}\text{C}$		1.36	1.87	mΩ
RDS(ON)Q5	Inverter Low Side MOSFETs Q5 (See Note 3)	$V_{GS} = 10 \text{ V}, I_D = 80 \text{ A}, T_j = 25^{\circ}\text{C}$		1.57	2.08	mΩ
RDS(ON)Q6	Inverter Low Side MOSFETs Q6 (See Note 3)	$V_{GS} = 10 \text{ V}, I_D = 80 \text{ A}, T_j = 25^{\circ}\text{C}$	12	1.86	2.32	mΩ
IDSS	Inverter MOSFETs (UH,UL,VH,VL,WH,WL)	$V_{GS} = 0 \text{ V}, V_{DS} = 32 \text{ V}, T_j = 25^{\circ}\text{C}$	Ser.	101	1.0	μΑ
Igss	Inverter MOSFETs Gate to Source Leakage Current	V <sub>es</sub> = ±20 V	511/2 X		±100	nA
Total loc	pp resistance VLINK(+) - V0 (-)	$V_{GS} = 10 \text{ V}, I_D = 80 \text{ A}, T_j = 25^{\circ}\text{C}$	-	4.69	5.5	mΩ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product

# TEMPERATURE SENSE (NTC Thermistor)

Symbol	Test Conditions	Test Time	Min	Тур	Max	Unit
Voltage	Current = 1 mA, Temperature = 25°C	T = 0.5 ms	7.5	_	12	V

# CURRENT SENSE RESISTOR

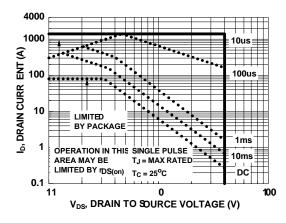
Ī	Symbol	Test Conditions	Test Time	Min	Тур	Max	Unit
	Resistance	Current Sense resistor current = 80 A	T = 0.5 ms	0.46	-	0.53	mΩ

performance may not be indicated by the Electrical Characteristics of the listed test conditions, thress otherwise noted. I roduct performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. All MOSFETs have same die size and R<sub>DS(ON)</sub>. The different R<sub>DS(ON)</sub> values listed in the datasheet are due to the different access points available inside the module for R<sub>DS(ON)</sub> measurement. While the high side MOSFETs (Q1, Q2, Q3) have source sense wire bonds, the low side MOSFETs (Q4, Q5, Q6) do not have source sense wire bonds, thus resulting in higher R<sub>DS(ON)</sub> values.

#### TYPICAL CHARACTERISTICS

(Generated using MOSFETs assembled in a TO263 package, for reference purposes only.)

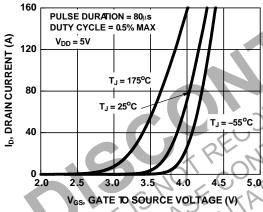


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Figure 3. Forward Bias Safe Operating Area

NOTE: Refer to Application Notes AN7514 and AN7515

Figure 4. Unclamped Inductive Switching Capability



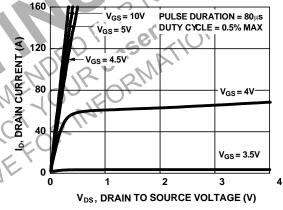
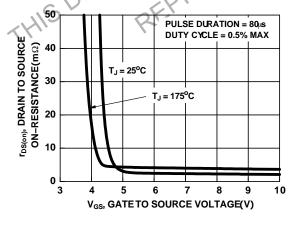


Figure 5. Transfer Characteristics





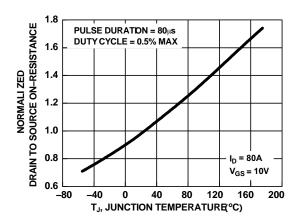
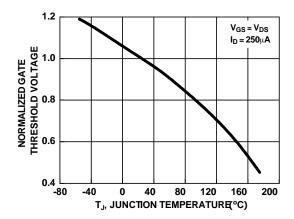


Figure 7. Drain to Source On–Resistance Variation vs Gate to Source Voltage

Figure 8. Normalized Drain to Source On Resistance vs Junction Temperature

#### **TYPICAL CHARACTERISTICS**

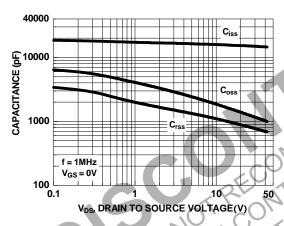
(Generated using MOSFETs assembled in a TO263 package, for reference purposes only.)



1.15 NORMALIZED DRAIN TO SOURCE  $I_D = 250 \mu A$ **BREAKDOWN VOLTAGE** 1.10 1.05 1.00 0.95 0.90 -80 0 40 80 120 160 200 T<sub>J</sub>, JUNCTION TEMPERATURE (°C)

Figure 9. Normalized Gate Threshold Voltage vs Junction Temperature

Figure 10. Normalized Drain to Source Breakdown Voltage vs Junction Temperature



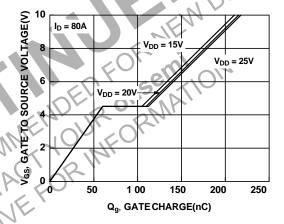


Figure 11. Capacitance vs Drain to Source Voltage

Figure 12. Gate Charge vs Gate to Source Voltage

#### **MECHANICAL CHARACTERISTICS AND RATINGS**

		Limits			
Parameter	Condition	Min	Тур	Max	Unit
Device Flatness	Note Figure 13.	0	-	+200	μm
Mounting Torque	Mounting Screw: - M3, Recommended 0.7 N.m	0.6	0.7	0.8	N.m
Weight		-	20	_	g

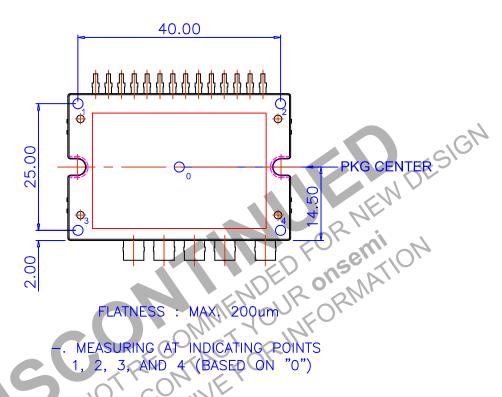
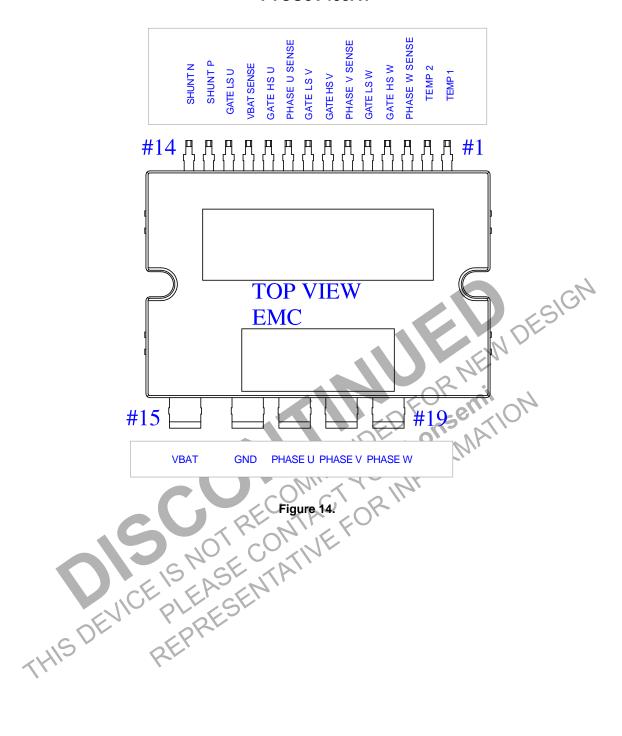


Figure 13. Flatness Measurement Position

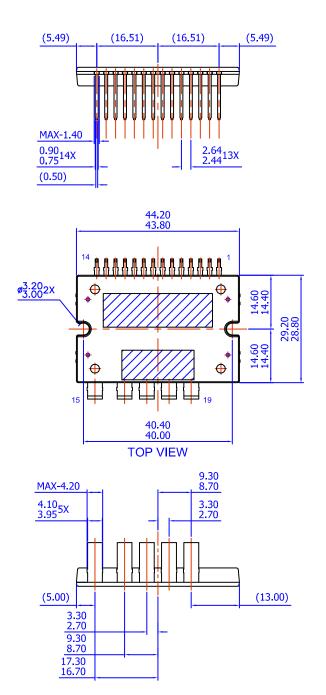
# ORDERING INFORMATION

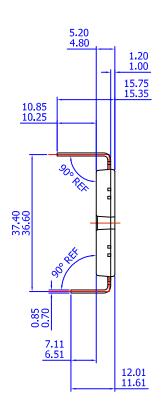
Device Marking	MOSFET	Packing Type	Quantity
FTCO3V455A1	PCF33478	Tube	11



#### APMCB-A19 / 19LD, APM, PDD STD DBC, DIP TYPE CASE MODCG ISSUE O

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